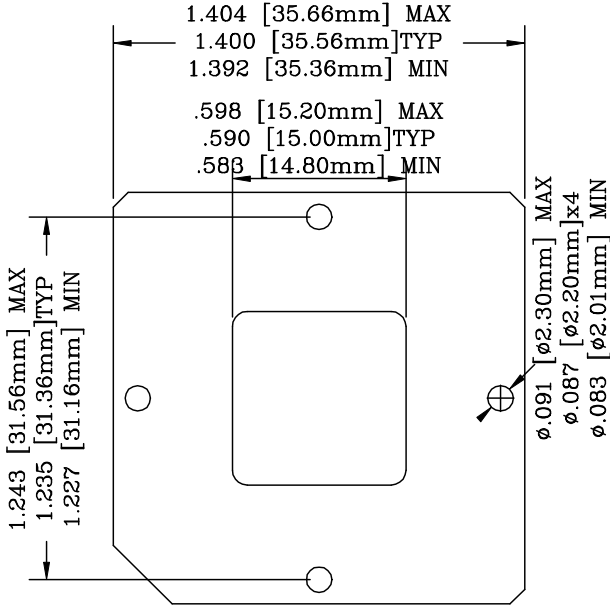


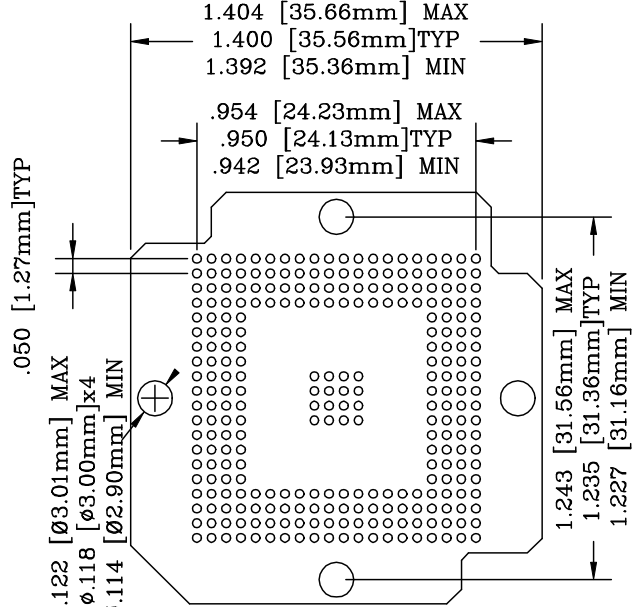
REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	2/14/01	A.F.

SCALE 2:1

SKT818
DOD 4818



RETENTION FRAME

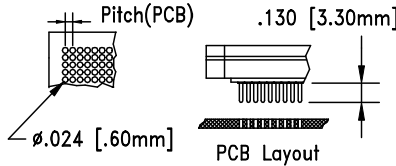
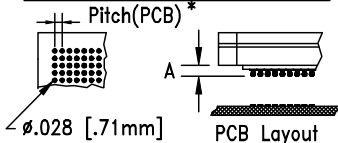


SOCKET

RECOMMENDED PAD LAYOUT

SOLDERTAIL STYLE	
REGULAR SMT STYLE XX = (-SM) YY = (-30)	RAISED SMT STYLE XX = (-RC) YY = (-29)

SOLDERTAIL = THRU HOLE STYLE
XX = (-ET) YY = (-70)



30= standard SMD ("A" = .047 [1.20mm])  
29= raised SMD ("A" = .197 [5.00mm])

BALL DIAMETER FOR:  
-29(RC) = .026 [0.66mm]  
-30(SM) = .026 [0.66mm]

PIN DIAMETER FOR:  
-70(ET) = .018 [0.45mm]

\* The pitch dimension depends on your Ball Grid Array Package

PACKAGE SPECIFICATIONS

PIN COUNT	= 272
LEAD PITCH	= 1.27mm
GRID SIZE	= 20x20
PACKAGE SIZE	= 27.00mm SQUARE

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED



**Emulation Technology, Inc.**

— VLSI and SMT ADAPTERS and ACCESSORIES —

2344 Walsh Avenue, Bldg. F  
Santa Clara, Ca 95051

TEL:(408)982-0660  
FAX:(408)982-0664

SHEET: 1 OF 1	DATE: 2/14/01	REVISION:	<b>ASSEMBLY DRAWING</b>
CHECKED: Perry Munroe	DRAWN: Aaron Fine	ITEM: S-BGA-20-272-XX	
DO NOT SCALE DRAWING			DESCRIPTION: BPW-272-2BG020-YY